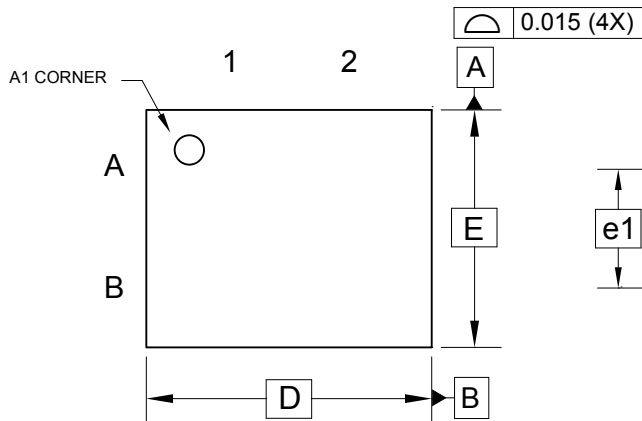
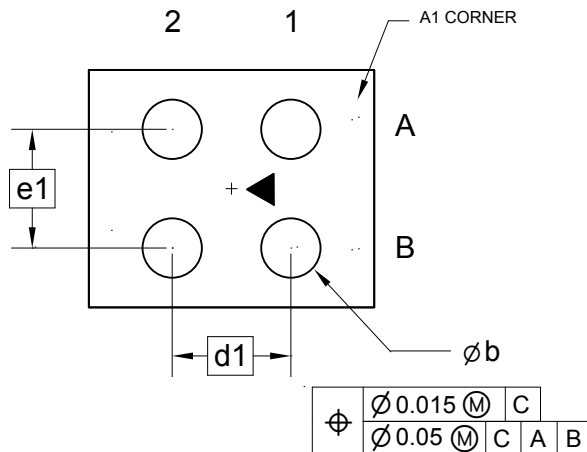


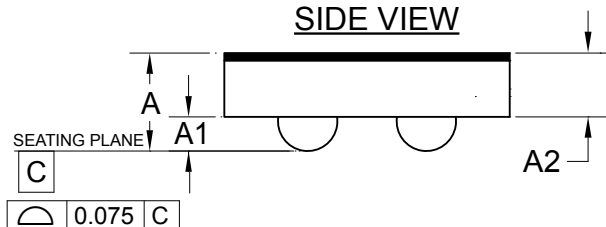
TOP VIEW



BOTTOM SIDE



SIDE VIEW



COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	—	0.095	—	
A2	—	0.200	—	3
D	Contact Microchip for details			
d1	0.400 BSC			
E	Contact Microchip for details			
e1	0.400 BSC			
b	0.170	0.185	0.200	

PIN ASSIGNMENT MATRIX

	1	2
A	SI/O	NC
B	GND	NC

- Note: 1. Dimensions are NOT to scale.
 2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
 3. Product offered with Back Side Coating (BSC)

12/3/15

TITLE

4U-6, 4-ball 2x2 Array, 0.40mm Pitch
 Wafer Level Chip-Scale Package (WLCSP) with BSC

GPC

GPH

DRAWING NO.

4U-6

REV.

B